

Title (en)

CU-CO-SI-BASED ALLOY SHEET, AND PROCESS FOR PRODUCTION THEREOF

Title (de)

LEGIERUNGSFOLIE AUF CU-CO-SI-BASIS SOWIE HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

TÔLE EN UN ALLIAGE À BASE DE CU-CO-SI ET SON PROCÉDÉ DE PRODUCTION

Publication

**EP 2578708 A1 20130410 (EN)**

Application

**EP 11789514 A 20110324**

Priority

- JP 2010127943 A 20100603
- JP 2011057216 W 20110324

Abstract (en)

The present invention provides a Cu-Co-Si system alloy sheet, being suitable for use in a variety of electronic device components, in particular, having excellent uniform adhesive property for plate. The copper alloy sheet for electronic materials, contains 0.5 to 3.0 mass% Co, 0.1 to 1.0 mass % Si, the balance being Cu and unavoidable impurities, wherein an average grain size in the center part of the sheet thickness is 20 µm or less, and the number of the crystal grain, being tangent to a surface of the sheet and having 45 µm or more of the length of major axis, is 5 or less in the area of 1 mm in a rolling direction.

IPC 8 full level

**C22C 9/06** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP US)

**C22C 9/06** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **H01B 1/026** (2013.01 - EP US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 2578708 A1 20130410**; **EP 2578708 A4 20140409**; CN 102666890 A 20120912; CN 102666890 B 20140507; JP 2011252216 A 20111215; JP 4708497 B1 20110622; TW 201200606 A 20120101; TW I422693 B 20140111; US 2013092297 A1 20130418; WO 2011152104 A1 20111208

DOCDB simple family (application)

**EP 11789514 A 20110324**; CN 201180003593 A 20110324; JP 2010127943 A 20100603; JP 2011057216 W 20110324; TW 100113320 A 20110418; US 201113581715 A 20110324